

规格书编号

SPEC NO :

产品规格书

SPECIFICATION

CUSTOMER 客户: _____
PRODUCT 产品: SAW FILTER
MODEL NO 型号: HDF110N2 F11
PREPARED 编制: _____ CHECKED 审核: _____
APPROVED 批准: _____ DATE 日期: 2007-12-21

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司
Shoulder Electronics Limited

更改历史记录 History Record

更改日期 Date	规格书编号 Spec. No.	产品型号 Part No.	客户产品型号 Customer No.	更改内容描述 Modify Content	备注 Remark

1. SCOPE

This specification shall cover the characteristics of SAW filter with F110N2 used for the page system.

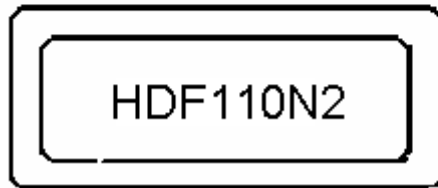
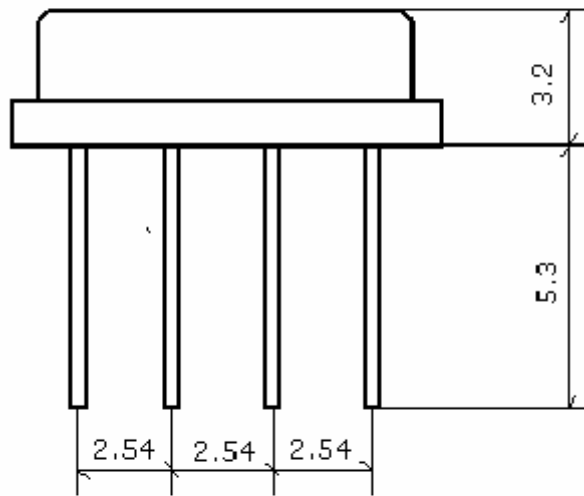
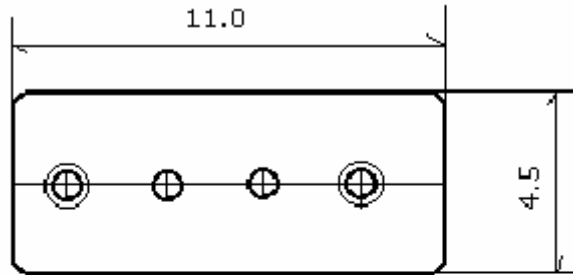
2. ELECTRICAL SPECIFICATION

DC Voltage VDC	10V
AC Voltage Vpp	10V50Hz/60Hz
Operation temperature	-40°C to +85°C
Storage temperature	-45°C to +85°C
RF Power Dissipation	0dBm

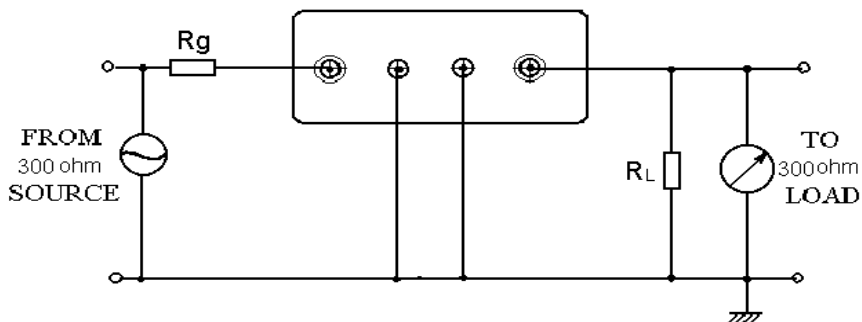
2.2 Electronic Characteristics

型号 Part Number	HDF110N2
中心频率(fo)(MHz) Nominal Center Frequency	110.592
3dB 带宽 Bandwidth(from fo)(KHz)	+/-350min
阻带衰减 Stop Band Attenuation (from peak level)(dB)	
1)fo-5.0MHz	50min
2)fo-3.5MHz	45min
3)fo+/-2.0MHz	30min
5)fo+3.5MHz	40min
6)fo+5MHz	40min
插入损耗(dB) Insertion Loss(at minimum loss point)	4.5max
群延时波动(fo+/-576KHz)(μ scc.) Group Delay Deviation	0.7
输入/输出阻抗 Input/output Impedance	300 Ω //1.2 μ H

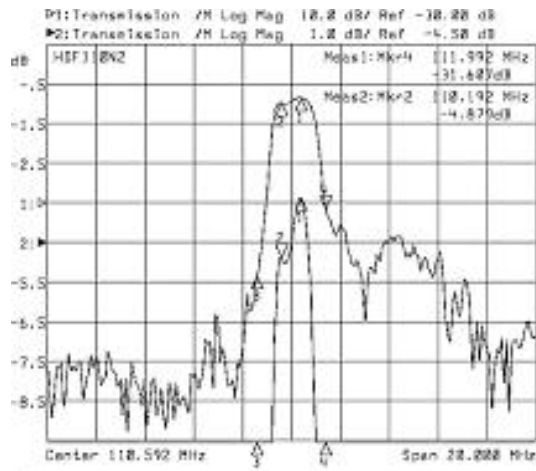
3.DIMENSION



4.TEST CIRCUIT



5. Typical Frequency Response



6. ENVIRONMENTAL CHARACTERISTICS

6-1 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of $+25^{\circ}\text{C}$ for 5 Minutes and a higher temperature of $+85^{\circ}\text{C}$ for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in 2.2.

6-2 Resistance to solder heat

Submerge the device terminals into the solder bath at $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in 2.2.

6-3 Solderability

Submerge the device terminals into the solder bath at $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in 2.2.

6-4 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. the filter shall fulfill the specifications in 2.2.

6-5 Vibration

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The filter shall fulfill the specifications in 2.2.

7. REMARK

7.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

7.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

7.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.